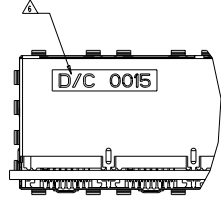
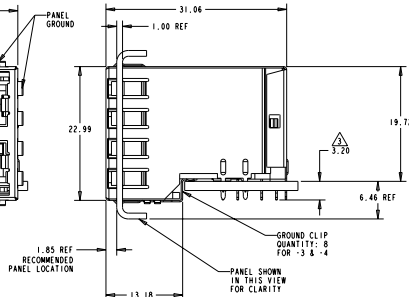
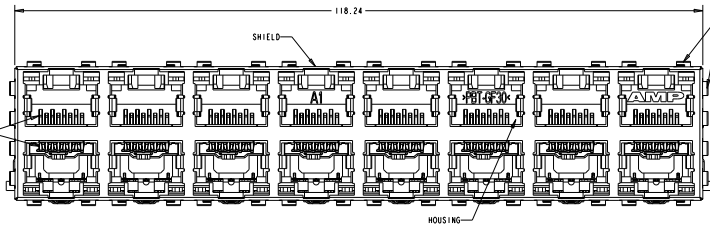
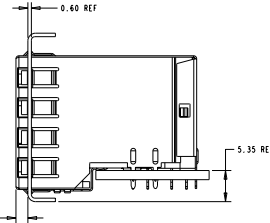


REV	DATE	REVISIONS	BY	CHK	APP
AA	00				
A		RELEASED	DRUCKMAN	LAN	JW
B		ECO-07-001858	DRUCKMAN	LAN	JW
C		ECO-08-019486	DRUCKMAN	A.L.	S.T.



**ATCA PANEL AND PRINTED CIRCUIT BOARD ASSEMBLY LAYOUT**

- MATERIALS:**  
 HOUSING: RPT POLYESTER, BLACK, UL 94V-0  
 TERMINALS: 0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 2.0µm MINIMUM THICK MATTE TIN IN COMPLIANT PIN TERMINAL AREA OVER 1.27µm MINIMUM THICK NICKEL UNDERPLATE  
 SHIELD: 0.25 THICK COPPER ALLOY PLATED WITH 2.03µm MINIMUM TIN OVER 1.27µm MINIMUM NICKEL  
 GROUND CLIP: 0.25 THICK COPPER ALLOY PRE-PLATED WITH 2.03µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68
- ⚠ MAXIMUM PIN LENGTH 3.40 FROM TOP SURFACE OF PC BOARD
  - ⚠ FINISHED PLATED THROUGH HOLE DIAMETER - ANNULAR RING DIAMETER 1.3 TO 1.5
  - ⚠ DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
  - ⚠ DATE CODE LOCATED ON REAR OF PART APPROXIMATELY AS SHOWN
  - ⚠ CONTACTS ARE NOT INTENDED TO BE ALIGNED WITH EACH OTHER

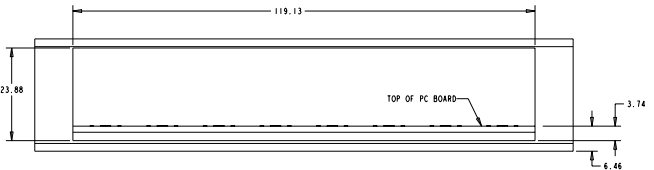


**AMC PANEL AND PRINTED CIRCUIT BOARD ASSEMBLY LAYOUT**

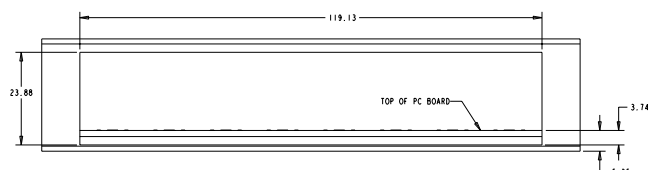
15.88	WITH GROUND CLIP	1888654-4
15.88	WITH GROUND CLIP	1888654-3 (SHOWN)
16.13	WITHOUT GROUND CLIP	1888654-2
16.13	WITHOUT GROUND CLIP	1888654-1
M D IM	DESCRIPTION	PART NUMBER

DRAWING NO: 1888654-3 REV: A DATE: 07/19/08 BY: DRUCKMAN CHECKED: DRUCKMAN APPROVED: DRUCKMAN TERA ELECTRONICS CORPORATION HARRISBURG, PA 17105-3600	PART NUMBER: 1888654-3 DESCRIPTION: STACKED MOD JACK ASSEMBLY, 2 X 8, 8 POSN, SHIELDED, PANEL GROUND, OFFSET, CAT 5 DATE CODE: 00779 CUSTOMER DRAWING	TERA ELECTRONICS CORPORATION HARRISBURG, PA 17105-3600
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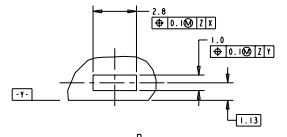
REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00	SEE SHEET 1			



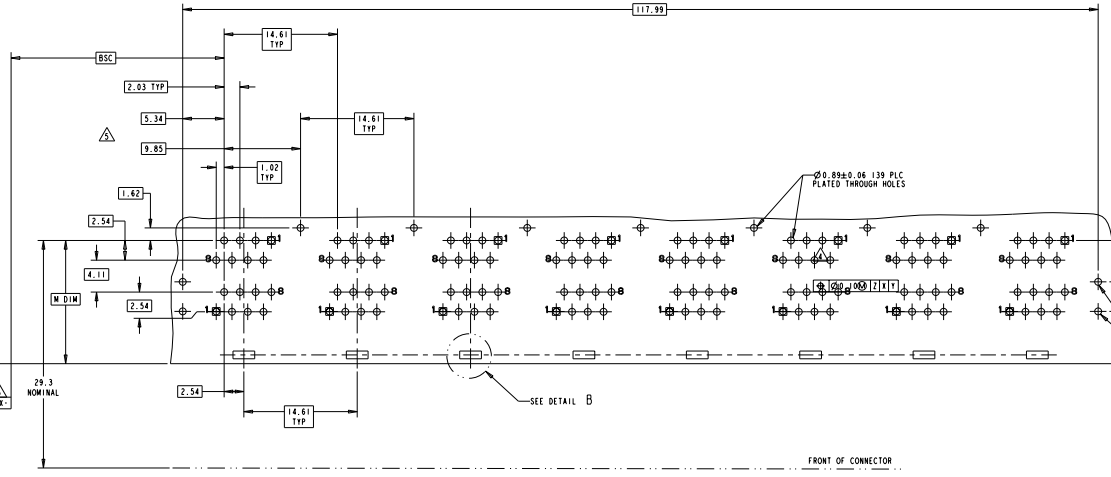
**ATCA PANEL AND PRINTED CIRCUIT BOARD LAYOUT**  
SCALE 2:1



**AMC PANEL AND PRINTED CIRCUIT BOARD LAYOUT**  
SCALE 2:1



**DETAIL B**  
SCALE 8:1  
PLATED PADS REQUIRED FOR 1888654-3 & -4 PRODUCT WITH GROUNDING CLIP



**PC BOARD LAYOUT (COMPONENT SIDE)**

DATE: 08/24/2018	BY: PDC ELECTRONICS CORPORATION	REV: AA	DATE: 08/24/2018	DESCRIPTION: SEE SHEET 1
<b>PC BOARD LAYOUT (COMPONENT SIDE)</b> SCALE 2:1		<b>STACKED MOD JACK ASSEMBLY, 2 X 8, 8 POSN. SHIELDED, PANEL GROUND, OFFSET, CAT 5</b> SCALE 2:1 REV: AA DATE: 08/24/2018 BY: PDC ELECTRONICS CORPORATION APP: [Signature]		